



AT&S

CONSISTENCY IN **CHANGE**



Berenberg Conference USA 2021
Investor and Analyst Presentation

19th May 2021

LEADING PROVIDER OF HIGH-END PCBs & IC SUBSTRATES

Well positioned for the future

Unique market position

- Broad product portfolio to serve all growth markets
- Long-standing customer relationships with technology and market leaders
- Technology innovator due to continuous R&D efforts
- Quality benchmark with outstanding process know-how, productivity and efficiency

Growth oriented strategy

- Megatrend-driven markets with attractive growth potential
- Address growth opportunities with incremental investments
- Constant outperformance of the PCB & substrates market

€1.2 bn revenue FY 20/21

>€2 bn revenue FY 23/24

5

ABF substrates producer worldwide

3

in FY 24/25

2

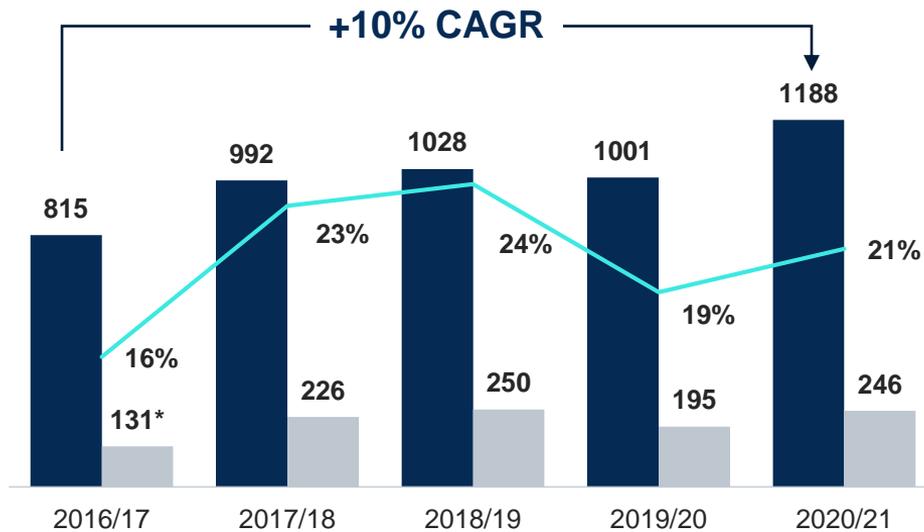
high-end PCB producer worldwide

ONE

of the leading high-end PCB producers worldwide

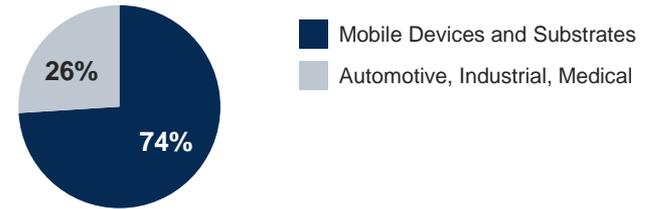
KEY FACTS

In € mn



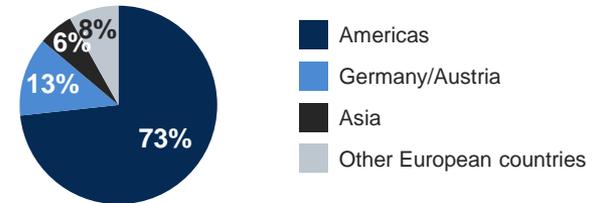
■ Revenue ■ EBITDA — EBITDA margin * Based on ramp-up effects for new plants in China

Revenue split by segment: FY 20/21



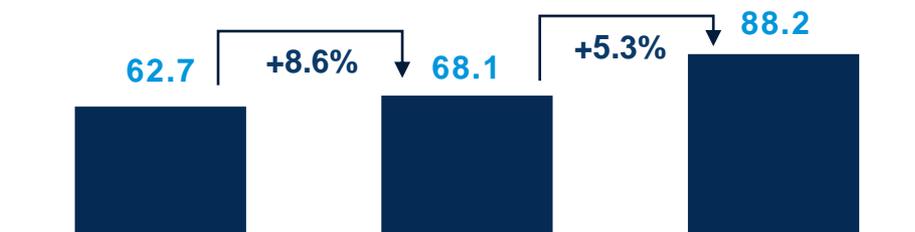
Revenue split by customer: FY 20/21

Based on customer's headquarters



AT&S OUTPERFORMS PCB & IC SUBSTRATES* MARKET GROWTH

in US\$ bn



	CY 2020	YoY	CY 2021	CAGR	CY 2026
Automotive	6.2	+10.0%	6.8	+6.2%	9.2
Aviation	2.8	+3.9%	2.9	+3.3%	3.4
Industrial	2.5	+5.8%	2.6	+3.8%	3.2
Medical	1.3	+5.0%	1.3	+3.6%	1.6
IC Substrates*	7.7	+23.0%	9.4	+9.1%	14.5
Communication	18.0	+7.3%	19.3	+6.0%	25.8
Computer	16.4	+5.2%	17.3	+3.1%	20.2
Consumer	8.0	+6.9%	8.5	+4.1%	10.4

+8.6% market growth
YoY from 2020 to 2021

+18.8% AT&S growth
YoY in the FY 2020/2021

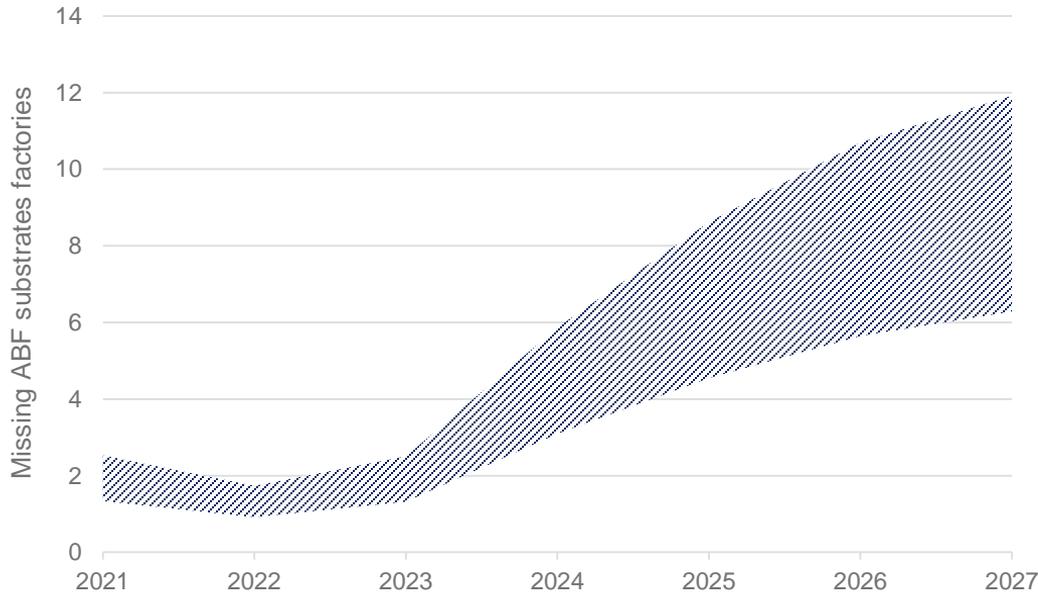
AT&S will outperform the market with
an annual growth of
>15% until 2025

Source: Prismark 03/2021

* only containing high-end IC substrates

CONTINUOUS GROWTH IN ABF SUBSTRATES DEMAND

Actual gap of required ABF substrates factories to satisfy demand



- Actual gap depends on actual mix in product and technology demand
- Increasing **complexity of high-end** products leads to ongoing strong ABF substrates demand
- Complexity requires **increasing layer count and larger products**
- Current supply shortage is predominantly in high-end products
- Especially **server and AI applications** drive the demand

Source: AT&S Internal assessment
One factory corresponds to four production lines

STRATEGIC BUSINESS DRIVERS



GAME CHANGERS ARE DRIVING OUR BUSINESS

New technologies and systems bring a significant data volume increase



5G

Big Data

Artificial Intelligence

Internet of Things

MOBILE DEVICES AND SUBSTRATES

CAGR 2021 – 2026

Consumer +4.1%
Computer +3.1%
Communication +6.0%

CAGR 2021 – 2026
IC Substrates +9.1%



Product/Application

AT&S Technologies/Solutions

Product/Application

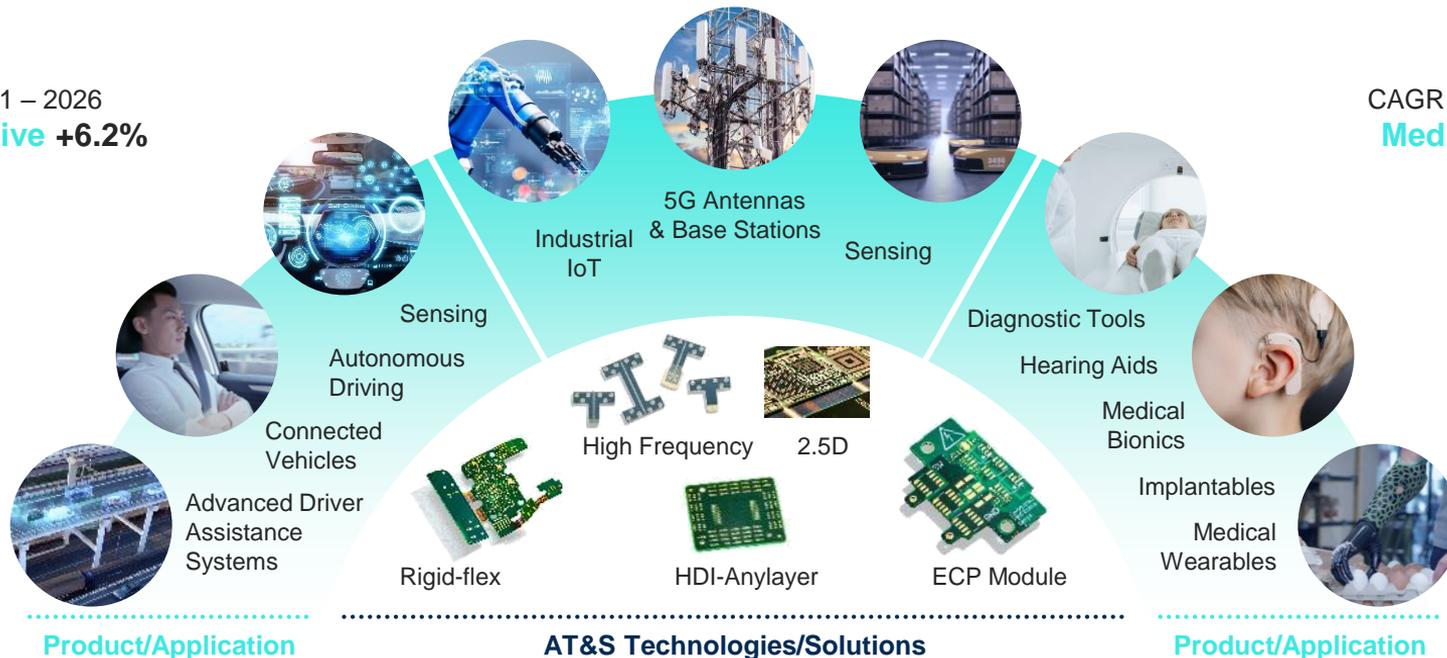
* PCB/IC Substrates Market Growth: CAGR 2021-2026

AUTOMOTIVE – INDUSTRIAL – MEDICAL

CAGR 2021 – 2026
Industrial +3.8%

CAGR 2021 – 2026
Automotive +6.2%

CAGR 2021 – 2026
Medical +3.6%



R&D – BASIS FOR TECHNOLOGY LEADERSHIP

10%

R&D rate
(corresponds to
€ 119 mn)

R&D

HQ Austria
Development up to
series production at
the production sites

429

Patents

21%

Vitality Index*

International
R&D partners



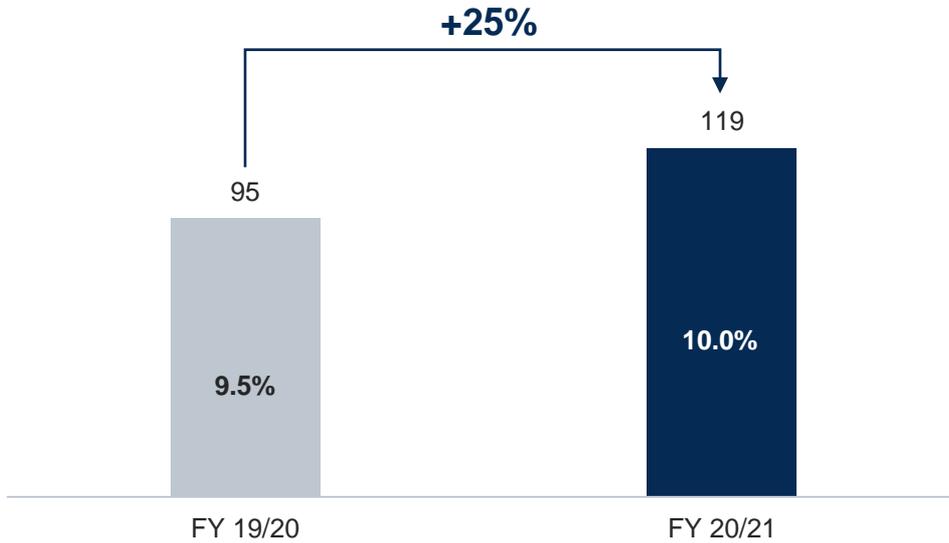
Status: FY 2020/21

*Share of revenue of technologically innovative products made in the last three years (previously: Innovation Revenue Rate)

R&D INVESTMENTS

A key revenue and margin driver

in € mn



€ 246 mn revenue
with new products

Miniaturisation
and functional
integration

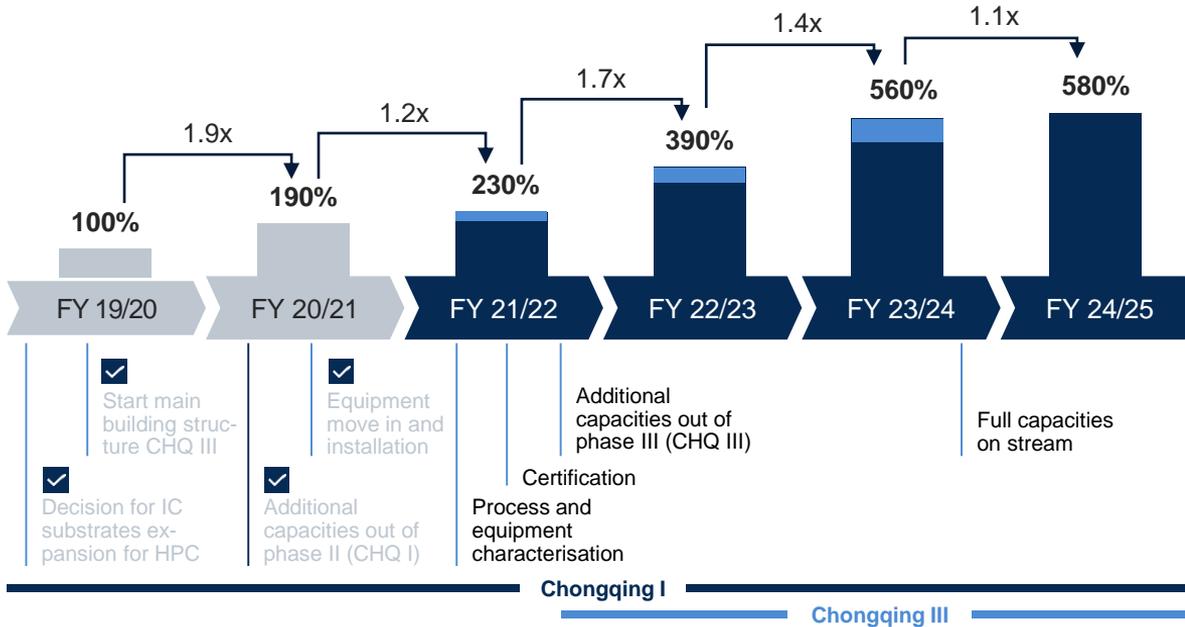
Fast signal
transmission

Performance and
performance
efficiency

Manufacturing of
the future

RAMP OF CHONGQING III EARLIER THAN EXPECTED

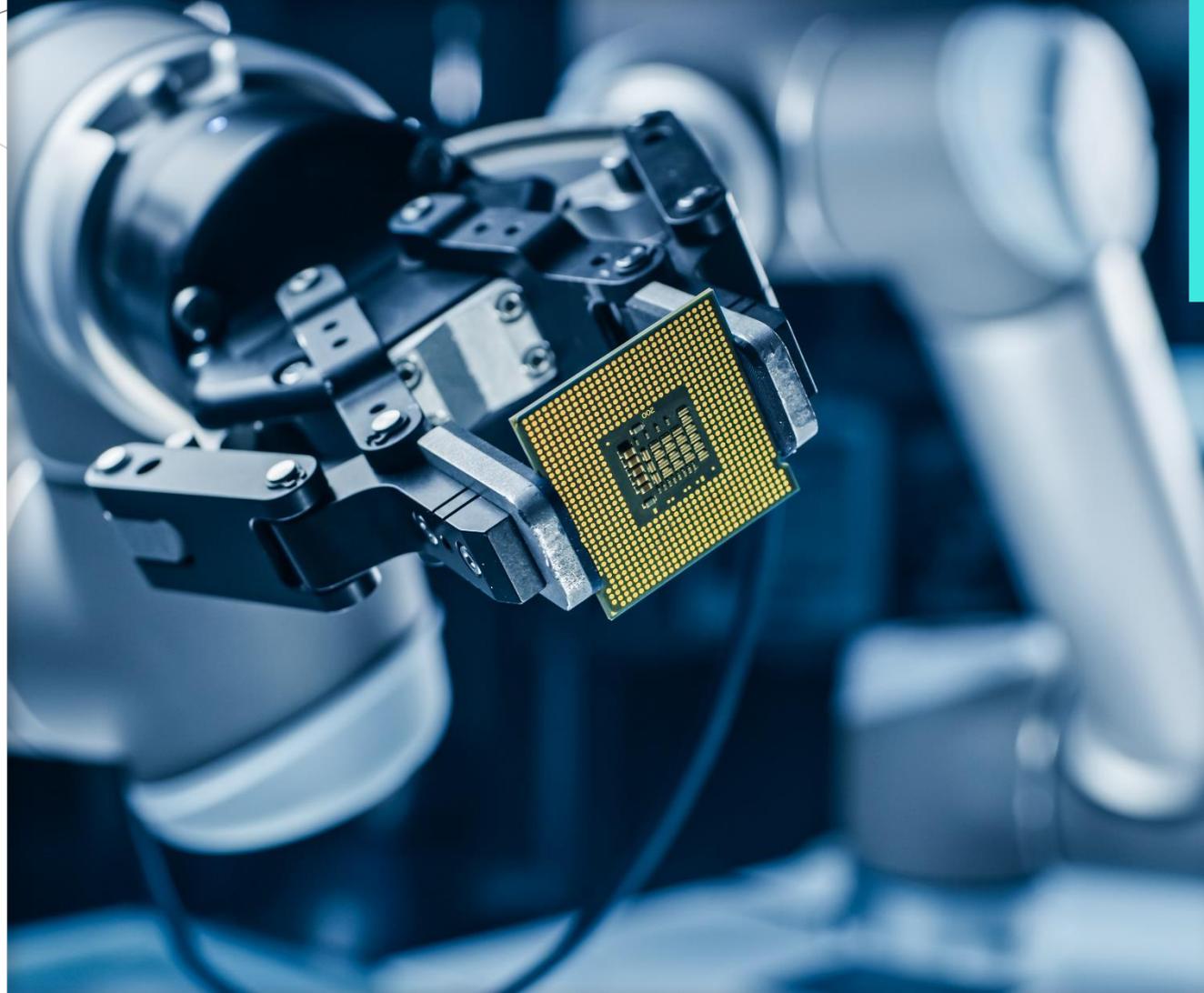
ABF substrates output capacity



- CHQ III: Production will already be starting in FY 21/22
- Additional € 200 mn investment in CHQ III
- Full capacities available with the beginning of CY 2024 (Q4 23/24)

Additional output capacity due to investment increase and earlier production start in CHQ III

RESULTS FY 20/21



KEY DEVELOPMENTS FY 20/21

Strong full-year results demonstrate AT&S resilience and agility

**Growing
profitably
with served
markets**

- Additional capacities and strong demand drive ABF substrates business
- Mobile applications supported by customer and application diversification
- PCBs for modules contribute to overall revenue growth
- Automotive with ongoing recovery and Q4 above last year
- Medical & Healthcare with stable performance due to improved demand
- Industrial segment with positive development thanks to better product mix
- Capacity expansion in Chongqing faster than expected

FY 20/21 RESULTS SUMMARY

Revenue at historic high

Revenue +19%

€1,188 mn

- Five year CAGR 8%
- Negative FX effects of € 37 mn

EBITDA margin +130 bps

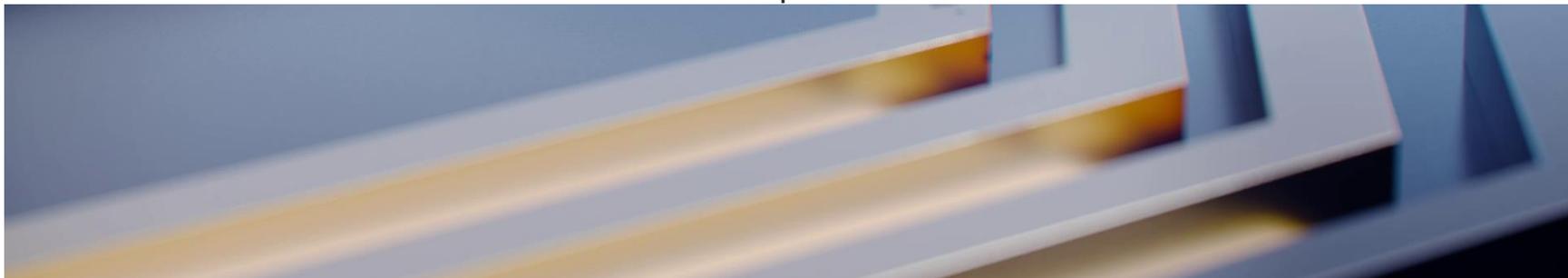
20.7%

- Strong EBITDA margin despite headwinds from COVID-19 impacts

ROCE +300 bps

5.8%

- Driven by strong operating result



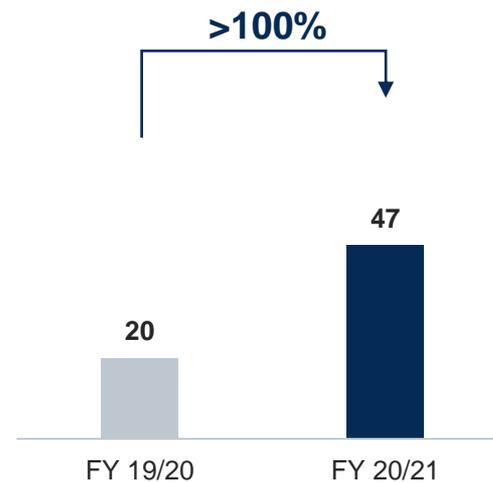
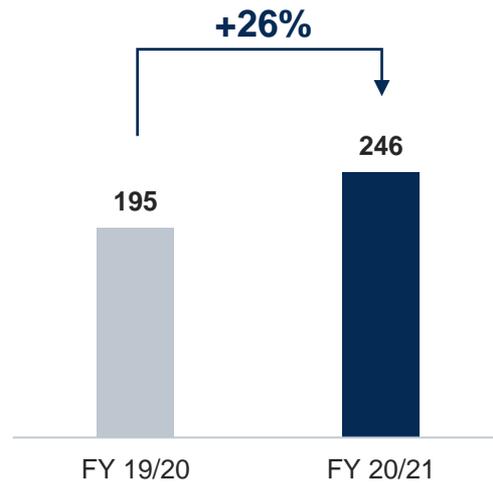
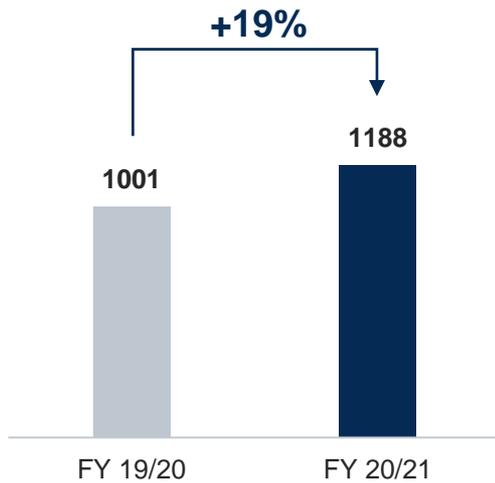
FY 20/21 RESULTS SUMMARY

Revenue

EBITDA

Net profit

in € mn



QUARTERLY DEVELOPMENT

in € mn



Highest Q4 revenue in history

Part of **seasonality mitigated** by growing IC substrates business

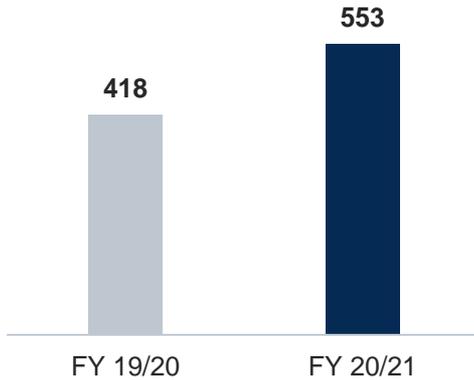
Profitability clearly improved

FY 20/21 FINANCIAL POSITION

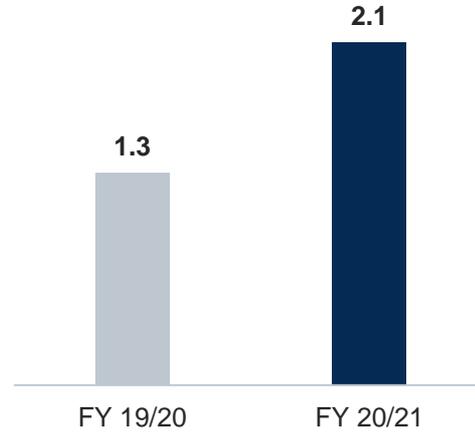
Solid financial structure for future growth

Cash & cash equivalents

in € mn



Net debt/EBITDA



Balancing capital allocation

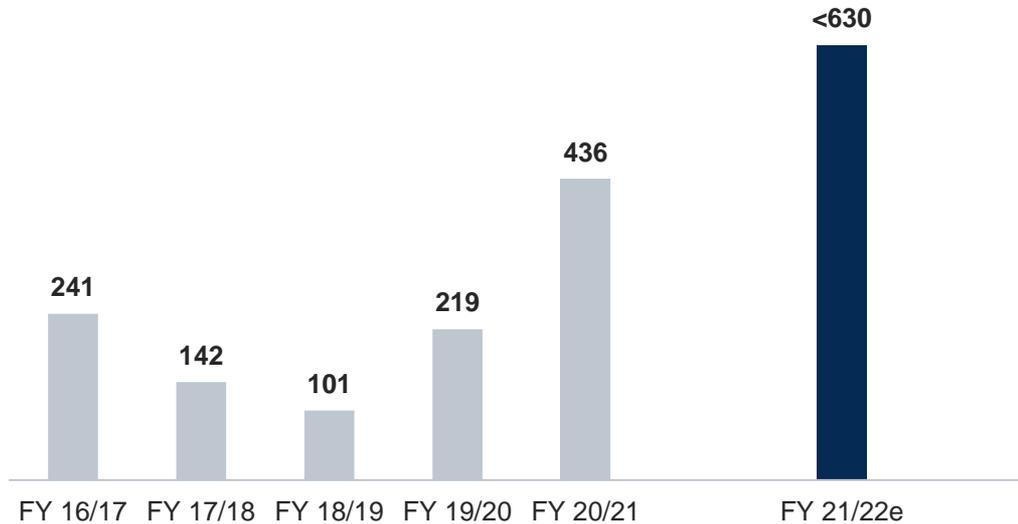
- Deploying capital with clear approach to invest in strategic growth markets
- Increasing net debt level by € 262 m in FY 20/21 due to investments in additional IC substrates capacities

Sound investment decisions to generate strong operating and free cash flow in the future.

NET CAPEX

Investments in IC substrates and module PCBs consistently continued

in € mn



Capex outlook 2021/22

- Depending on market developments CAPEX for maintenance and tech upgrade of up to € 100 m
- CAPEX for strategic projects of up to € 450 m plus € 80 m due to timing variances

BALANCE SHEET

€ mn	31.03.2020	31.03.2021	Change in %
Total assets	1,854	2,390	+29%
Equity	760	802	+6%
Equity ratio	41%	34%	-740bps
Net debt	247	509	>100%

Ongoing expansion and technology upgrades main driver for increase in total assets

Increase in total assets weighs on equity ratio

Higher CAPEX feeds into liquidity and drives up net debt

CASH FLOW

€ mn	FY19/20	FY 20/21	Change in %
CF from operating activities	185	185	-0.3%
CF from investing activities	-117	-340	>-100%
CF from financing activities	18	304	>100%
Operating free CF	-33	-251	>-100%

Stable as higher operating result is offset by higher working capital

Operating free CF mainly driven by higher CAPEX

GUIDANCE FY 21/22

Further growth ahead

FY 21/22	
Growth	Revenue growth of 13 – 15%
Profitability	Adjusted EBITDA margin of 21 – 23% Adjustment: start-up effects of the Chongqing project with an amount of appr. € 40 mn
CAPEX	<ul style="list-style-type: none">▪ Maintenance and tech-upgrades € 100 mn▪ CAPEX from PY (timing variances) € 80 mn▪ Expansion projects € 450 m
Dividend proposal	€ 0.39 per share (for FY 20/21)

ANNEX

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MARKET PLAYERS IN THE HIGH-END SEGMENT

HDI Technology (2019)

1	Compeq
2	AT&S
3	TTM
4	Unimicron
5	Tripod
6	Meiko
7	Zhen Ding
8	Korea Circuit

ABF Substrates (2019)

1	Ibiden
2	Unimicron
3	SEMCO
4	Shinko
5	AT&S
6	Kyocera
7	Nan Ya PCB
8	Kinsus

Source: Prismark, JMS, AT&S assessment

AT&S SOLUTIONS FOR THE ELECTRONICS INDUSTRY

Module Design

Chip Manufacturing | Front-end

Chip Assembly & Test | Back-end

PCB Manufacturing

Substrate Manufacturing

Product/Module Assembly

Product Ownership

Design houses

OEMs

Fab-less IC Players

Wafer Foundries

OSATs

PCB

00

ODM/EMS/OSATs

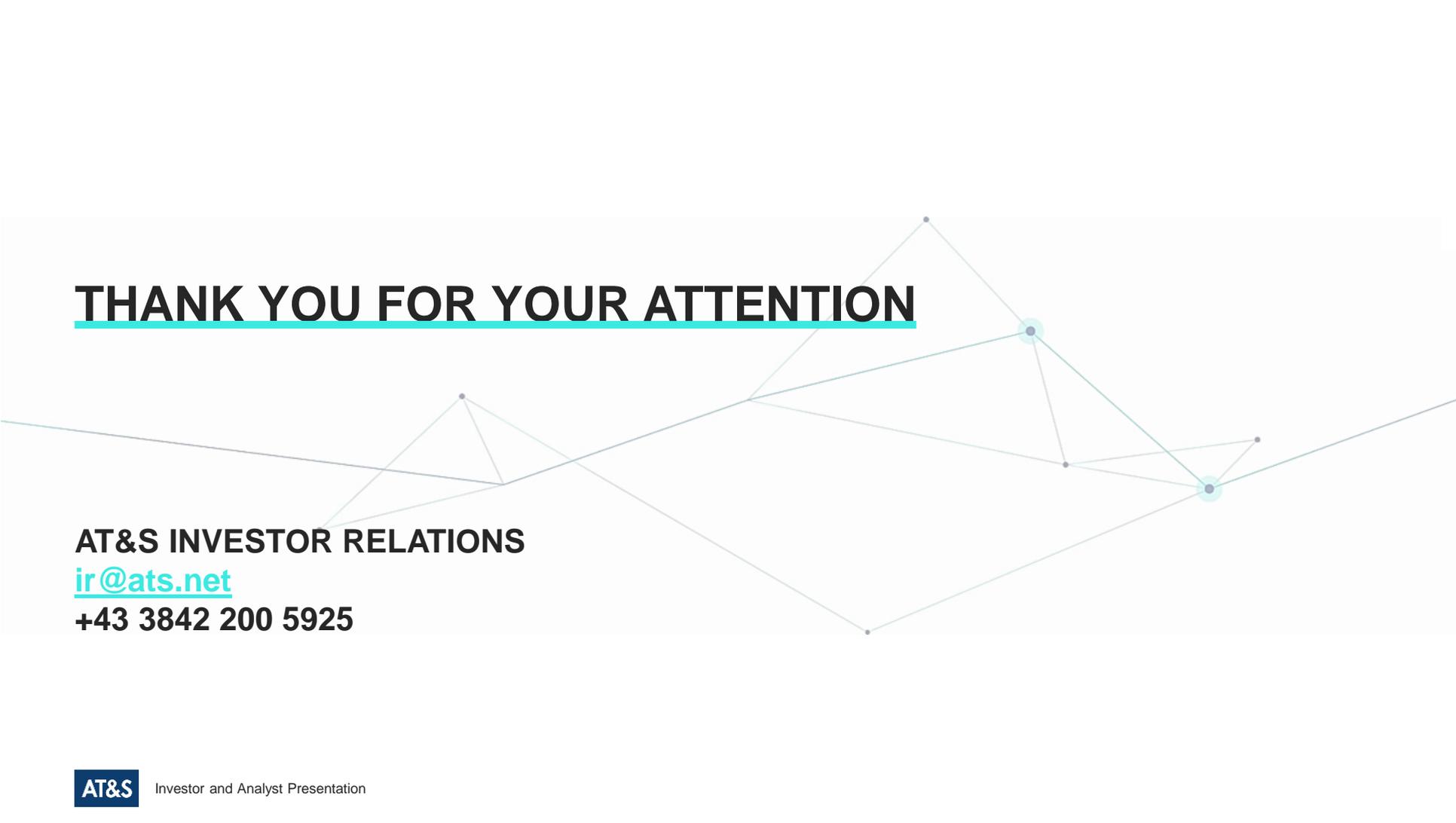
OEMs

Module Integration Service Provider

02

Module Board Manufacturer (SLP)

01



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AT&S INVESTOR RELATIONS

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